



## SSC8164GS9

### N-Channel Small Switching MOSFET with ESD Protection

#### ➤ Features

V <sub>DS</sub>	V <sub>GS</sub>	R <sub>DS(ON)</sub> Typ.	I <sub>D</sub>	ESD
60V	±20V	1Ω@10V	0.3A	500V
		1.25Ω@4V5		

#### ➤ Description

This device is an N-Channel enhancement mode MOSFET, with low on-resistance, fast switching speed and low threshold voltage, it is ideal for portable equipment.

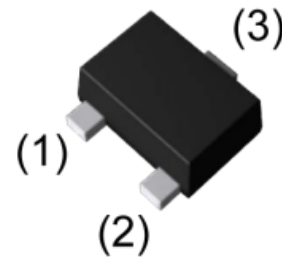
#### ➤ Applications

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers
- Display, Memories, Transistors, etc.
- Battery Operated System
- Solid-State Relays

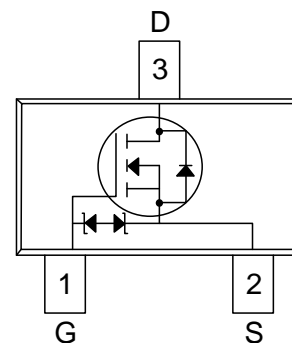
#### ➤ Ordering Information

Device	Package	Shipping
SSC8164GS9	SOT-723	8000/Reel

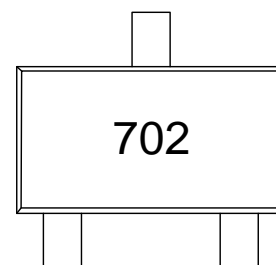
#### ➤ Pin configuration



**SOT-723**



**Pin Configuration (Top View)**



**Marking**



➤ **Absolute Maximum Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Ratings	Unit
$V_{DSS}$	Drain-to-Source Voltage	60	V
$V_{GSS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current <sup>a</sup>	0.3	A
$I_{DM}$	Pulsed Drain Current <sup>b</sup>	0.8	A
$P_D$	Power Dissipation <sup>c</sup>	0.5	W
$P_{DSM}$	Power Dissipation <sup>a</sup>	0.25	W
$T_J$	Operation junction temperature	-55~150	$^{\circ}\text{C}$
$T_{STG}$	Storage temperature range	-55~150	$^{\circ}\text{C}$

➤ **Thermal Resistance Ratings ( $T_A=25^{\circ}\text{C}$  unless otherwise noted)**

Symbol	Parameter	Maximum	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance <sup>a</sup>	510	$^{\circ}\text{C}/\text{W}$
$R_{\theta JC}$	Junction-to-Case Thermal Resistance	255	$^{\circ}\text{C}/\text{W}$

Note:

- The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz.copper, in a still air environment with  $T_A=25^{\circ}\text{C}$ . The value in any given application depends on the user is specific board design. The power dissipation is based on the  $t \leq 10\text{s}$  thermal resistance rating.
- Repetitive rating, pulse width limited by junction temperature.
- The power dissipation  $P_D$  is based on  $T_{J(MAX)}=150^{\circ}\text{C}$ , using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.

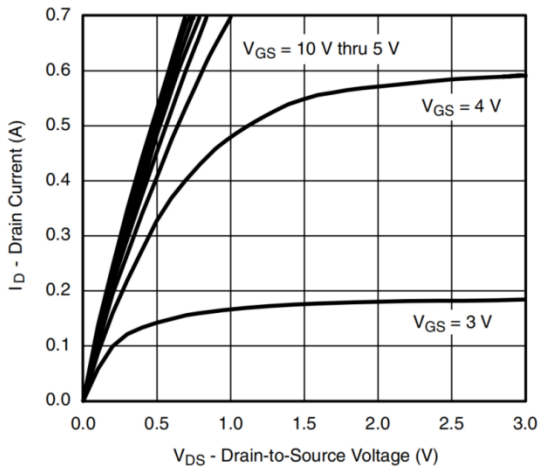


➤ **Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**

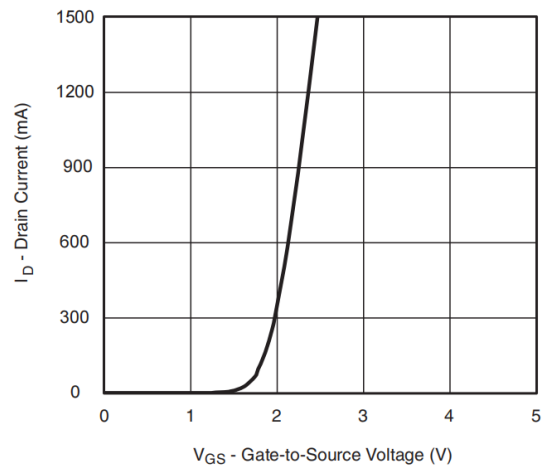
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	60			V
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250uA	0.75	1	1.25	V
Drain-Source On-Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 0.5A		1	2.5	Ω
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 0.5A		1.25	3.5	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 0.2A		1.7	4	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60V, V <sub>GS</sub> = 0V			1	μA
Gate-Source Leak Current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±10	μA
Transconductance	G <sub>FS</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.2A		0.1		s
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = 0.2A			1.3	V
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz		30		pF
Output Capacitance	C <sub>OSS</sub>			6		
Reverse Transfer Capacitance	C <sub>RSS</sub>			2.9		
Turn-on Delay Time	T <sub>D(ON)</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 10V, I <sub>D</sub> = 0.1A		25		ns
Rise Time	T <sub>r</sub>			10		
Turn-off Delay Time	T <sub>D(OFF)</sub>			35		
Fall Time	T <sub>f</sub>			20		
Total Gate Charge	Q <sub>G</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 0.2A		0.4		nC
Gate to Source Charge	Q <sub>GS</sub>			0.1		
Gate to Drain Charge	Q <sub>GD</sub>			0.11		



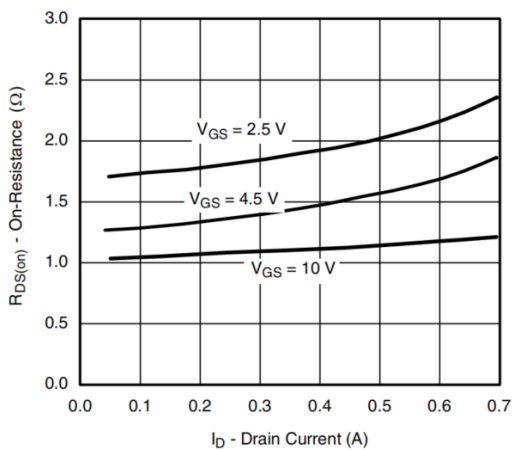
➤ **Typical Performance Characteristics (T<sub>A</sub>=25°C unless otherwise noted)**



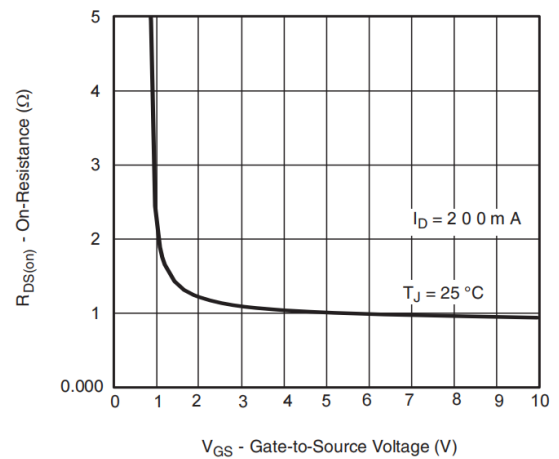
**Output Characteristics**



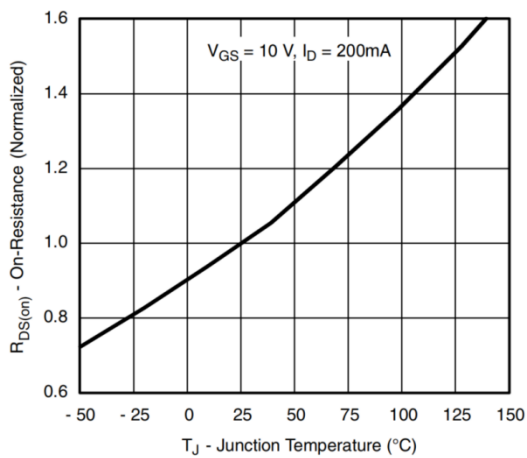
**Transfer Characteristics**



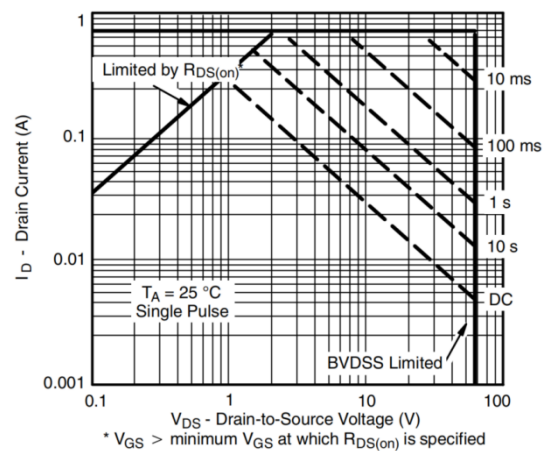
**On-Resistance vs. Drain Current**



**On-Resistance vs. Gate-to-Source Voltage**

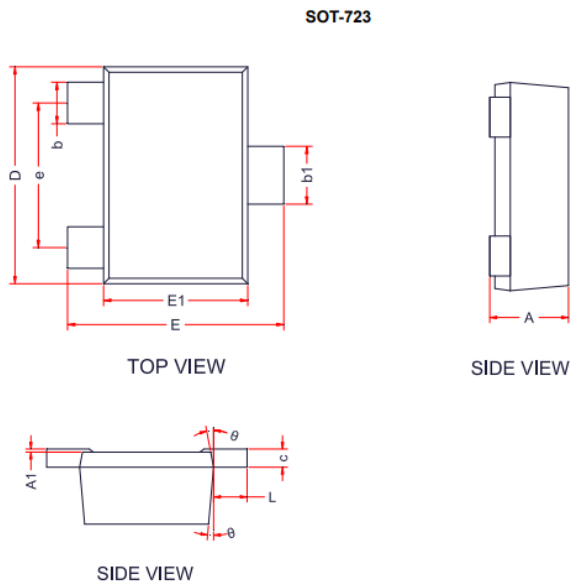


**On-Resistance vs. Junction Temperature**



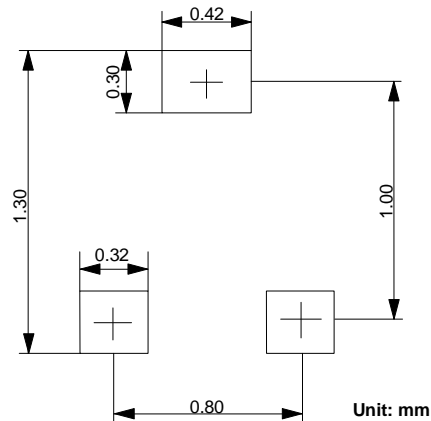
**Safe Operating Area**

## ➤ Package Information



DIM	Millimeters		
	Min.	Typ.	Max.
<b>A</b>	0.43	-	0.55
<b>A1</b>	0.00	-	0.05
<b>b1</b>	0.27		0.37
<b>b</b>	0.17	-	0.27
<b>c</b>	0.08	0.13	0.18
<b>D</b>	1.15	1.20	1.25
<b>E</b>	1.15	1.20	1.25
<b>E1</b>	0.75	0.8	0.85
<b>e</b>	0.80Ref.		
<b>L</b>	0.15	0.2	0.25
<b>θ</b>	7°Ref.		

## ➤ Suggested Pad Layout





➤ **History Version**

V2.0	First edition	2021-5-08
V2.1	Modify Typical Performance Characteristics	2023-12-22

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